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A											<table><tr><th>Layer</th><th>Name</th><th>Material</th><th>Thickness</th><th>Constant</th><th>Board Layer Stack</th></tr><tr><td>1</td><td>Top Overlay</td><td></td><td></td><td></td><td></td></tr><tr><td>2</td><td>Top Solder</td><td>Solder Resist</td><td>0.40mil</td><td>3.5</td><td></td></tr><tr><td>3</td><td>Top Layer</td><td>Copper</td><td>1.40mil</td><td></td><td></td></tr><tr><td>4</td><td>Dielectricl</td><td>FR-4</td><td>59.20mil</td><td>4.8</td><td></td></tr><tr><td>5</td><td>Bottom Layer</td><td>Copper</td><td>1.40mil</td><td></td><td></td></tr><tr><td>6</td><td>Bottom Solder</td><td>Solder Resist</td><td>0.40mil</td><td>3.5</td><td></td></tr><tr><td>7</td><td>Bottom Overlay</td><td></td><td></td><td></td><td></td></tr></table>	Layer	Name	Material	Thickness	Constant	Board Layer Stack	1	Top Overlay					2	Top Solder	Solder Resist	0.40mil	3.5		3	Top Layer	Copper	1.40mil			4	Dielectricl	FR-4	59.20mil	4.8		5	Bottom Layer	Copper	1.40mil			6	Bottom Solder	Solder Resist	0.40mil	3.5		7	Bottom Overlay					A
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Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✕	2	59.00mil (1.499mm)	NPTH	Round
⊙	2	120.00mil (3.048mm)	NPTH	Round
□	5	7.87mil (0.200mm)	PTH	Round
○	22	10.00mil (0.254mm)	PTH	Round
▽	6	28.00mil (0.711mm)	PTH	Round
★	10	43.31mil (1.100mm)	PTH	Round
47 Total				

1300.00mil

1700.00mil

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HUL130	REV: A	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.
LAYER NAME = Mechanical100	TID #: N/A			
PLOT NAME = Fabrication Drawing	GENERATED : 4/11/2016 9:00:05 AM	TEXAS INSTRUMENTS		

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 0.2 mm  
MIN. VIA PAD SIZE: 24 MIL  
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL  
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:  
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:  
SILKSCREEN: ☒ TOP ☐ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER  
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE  
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK

PROJECT TITLE:  
TRS3122EUM

DESIGNED FOR:  
EUM

FILE NAME:  
HUL130.PcbDoc

ENGINEER: Michael Schultis	LAYOUT BY: Michael Schultis
SCALE: 1.00	ALTUM DESIGNER VERSION: 14